AMENDMENTS

In the Specification:

Page 2, please replace paragraph [0007] with the following:

[0007] In another aspect of the present invention, there is provided a process for fabricating an integrated circuit package. The process includes: fixing a heat slug to a substrate having a cavity therein, such that the heat slug spans the cavity; mounting a semiconductor die to the heat slug, at least a portion of the semiconductor die being disposed in the cavity; wire bonding the semiconductor die to ones of conductive traces of the substrate; encapsulating the wire bonds and the semiconductor die in an encapsulating material; and forming a ball grid array on the [[a]] first surface of the substrate such that bumps of the ball grid array are in electrical connection with ones of the conductive traces.

Page 3, please replace paragraph [0012] with the following:

[0012] In still another aspect, the package is stackable for reduction in motherboard area [[upon]] when mounted and to shorten the electrical signal bath between packages, thereby improving package to package communication.

Page 6, please replace paragraph [0038] with the following:

[0038] Next the semiconductor die 28 and wire bonds 30 are encapsulated in the encapsulating material 32 (Figure 5G). The encapsulating material 32 flows through the opening in the heat spreader, surrounding the wire bonds 30, the first semiconductor die 28 and the adapter 36, thereby protecting the wire bonds 30 as well as the semiconductor die 28. Clearly the top of the heat spreader is exposed for heat dissipation from the top of the package 20.